

L Number	Hits	Search Text	DB	Time stamp
-	35	sensor and manufactur\$ same process same integrated and substrate and second adj sensor	USPAT	2004/05/24 17:57
-	10	sensing same process same parameters same substrate same sensor	USPAT	2004/04/08 17:11
-	5	sensing same process same parameters same substrate same sensors	USPAT	2004/04/08 17:12
-	2	sensing same process same parameters same substrate same IC	USPAT	2004/04/08 17:12
-	1112	sensing same process same parameters	USPAT	2004/04/08 17:13
-	114	sensing same process same parameters and wafer	USPAT	2004/04/08 17:24
-	3738	sensors same wafer	USPAT	2004/04/08 17:24
-	2362	sensors same wafer and process and substrate	USPAT	2004/04/08 17:25
-	2135	sensors same wafer and process and substrate and first and second	USPAT	2004/04/08 17:25
-	209	sensors same wafer and process and substrate and first and second and thermal and pyro\$	USPAT	2004/04/08 17:25
-	42	sensors same wafer and process and substrate and first and second and thermal and pyro\$ and sample	USPAT	2004/04/13 13:10
-	1	6562185.pn.	USPAT	2004/04/13 13:10
-	326	702/117.ccls.	USPAT	2004/05/25 16:47
-	7	(6562185, 5683562, 6140689, 5830372, 6046398, 5795993, "4684884").pn.	USPAT	2004/05/18 14:10
-	9	(5907820, 5967661, 6033922, 6051443, 6244121, 6630995, 6693708, 6707545, "6721045").pn.	USPAT	2004/05/24 17:58
-	88	702/116.ccls.	USPAT	2004/05/25 16:47
-	120	702/132.ccls.	USPAT	2004/05/25 16:48
-	129	702/136.ccls.	USPAT	2004/05/25 16:48
-	154	702/184.ccls.	USPAT	2004/05/25 16:49
-	285	702/185.ccls.	USPAT	2004/05/25 16:49
-	218	438/5.ccls.	USPAT	2004/05/25 16:50
-	217	438/10.ccls.	USPAT	2004/05/25 16:50
-	86	438/11.ccls.	USPAT	2004/05/25 16:50
-	1048	438/14.ccls.	USPAT	2004/05/25 16:50
-	676	438/17.ccls.	USPAT	2004/05/25 16:50
-	377	438/18.ccls.	USPAT	2004/05/25 16:52
-	154	438/400.ccls.	USPAT	2004/05/25 16:53
-	62	156/345.13.ccls.	USPAT	2004/05/25 16:54